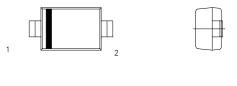
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SBD Type : **EP05H10**

FEATURES

- * JEDEC SOD-123 Package
- * Very Low profile 1.1mm Max
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * Low Thermal Resistance
- * Packaged in 8mm Tape and Reel

OUTLINE DRAWING





Maximum Ratings

Approx Net Weight:0.011g

| Rating | Symbol | EP05H10 | | | Unit | |
|-------------------------------------|----------------------|-------------|----------------|----------------------|------|--|
| Repetitive Peak Reverse Voltage | V _{RRM} | 60 | | | V | |
| Average Rectified Output Current | I_{O} | 0.48 | Ta=25°C * 1 | 50Hz Half Sine Wave, | A | |
| | | 0.50 | Tl=118°C | Resistive Load | | |
| RMS Forward Current | I _F (RMS) | 0.785 | | | A | |
| Surge Forward Current | I _{FSM} | 8 | 50Hz Half Sine | A | | |
| | | | Non-repetitive | | | |
| Operating JunctionTemperature Range | T_{jw} | -40 to +150 | | | °C | |
| Storage Temperature Range | Tstg | -40 to +150 | | | °C | |

Electrical • Thermal Characteristics

| Characteristics | Symbol | Conditions | Min. | Тур. | Max. | Unit | |
|----------------------|----------------------|--|------|------|------|------|--|
| Peak Reverse Current | I_{RM} | Tj= 25°C, V _{RM} = V _{RRM} | - | - | 50 | μΑ | |
| Peak Forward Voltage | $V_{\rm FM}$ | Tj= 25°C, I _{FM} =0.5A | - | - | 0.8 | V | |
| Thermal Resistance | Rth _(j-a) | Junction to Ambient * | - | - | 300 | °C/W | |
| | $Rth_{(j-l)}$ | Junction to Lead | - | - | 70 | C/W | |

^{*1:} Glass Epoxy Substrate Mounted (Soldering Lands=1x1mm,Both Sides)

(Tl: Lead Temperature)

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EP05H10 OUTLINE DRAWING (Dimensions in mm)

